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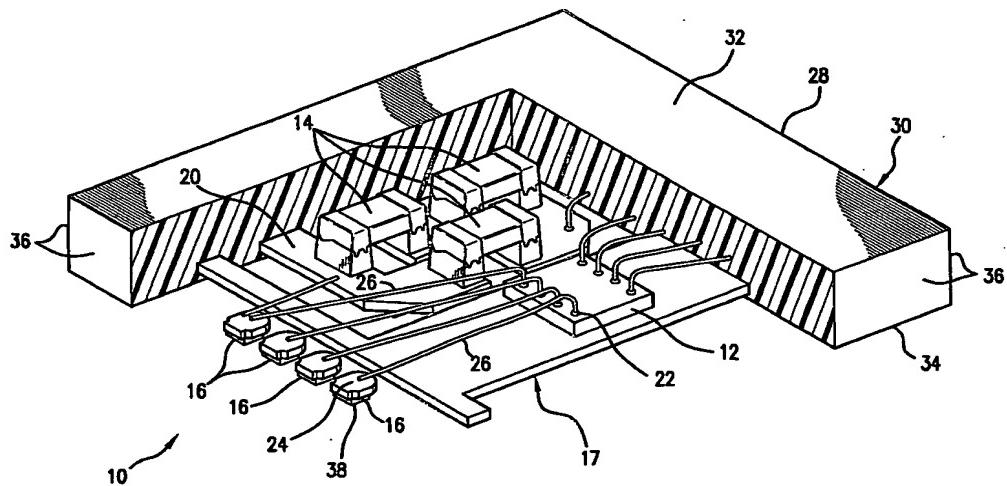
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(54) Title: LEAD FRAME WITH INCLUDED PASSIVE DEVICES



(57) Abstract: An semiconductor device package (10) includes a semiconductor device (die) (12) and passive devices (14) electrically connected to a common lead frame (17). The lead frame (17) is formed from a stamped and/or etched metallic structure and includes a plurality of conductive leads (16) and a plurality of interposers (20). The passive devices (14) are electrically connected to the interposers (20), and I/O pads (22) on the die (12) are electrically connected to the leads (16). The die (12), passive devices (14), and lead frame (17) are encapsulated in a molding compound (28), which forms a package body (30). Bottom surfaces (38) of the leads (16) are exposed at a bottom face (34) of the package (10).

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